

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3215	bump and "adhesive layer" and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:30
S2	1984	S1 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 08:04
S3	1671	S2 and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 08:04
S4	1671	S3 and @pd<"200031112"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 08:05
S5	741	S4 and (flexible and wir\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 08:06
S6	29	S5 and (flexible adj wir\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 12:10
S7	183	(257/733).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/07/28 09:02
S8	867026	flip chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:03
S9	102681	S8 and stud bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:03
S10	1125	S8 and "stud bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:03

S11	128	S10 and "adhesive layer"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:23
S12	93	S11 and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:23
S13	3	S12 and "flexible wiring substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:34
S14	508	"flexible wiring substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:34
S15	3	S14 and pad and "stud bump" and "adhesive layer"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 11:03
S16	11	S14 and "stud bump" and "adhesive layer"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:53
S17	33	S14 and "stud bump" and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 09:53
S18	136	"stud bump" and "adhesive layer"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 11:03
S19	11	S18 and "flexible wiring substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 11:12
S20	28	bump and "adhesive layer" and "flexible wiring substrate"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/28 11:13

S21	14798	(flexible adj wir\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 12:10
S22	528	(flexible adj wir\$3 adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 12:12
S23	494	S22 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:52
S24	149	S23 and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 12:45
S25	656843	package\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:30
S26	97597	bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:30
S27	141469	stud	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:30
S28	246004	gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:31
S29	501085	wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:31
S30	1248887	flexible	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:31

S31	2032830	substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:31
S32	9	S25 and (S30 adj S29 adj S31) and S26 and S27 and S28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:42
S33	7	S32 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:43
S34	168	S25 and S30 and S29 and S31 and S26 and S27 and S28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 08:42
S35	160	S34 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:03
S36	7499	(257/678,688,690,737,780,781). CCLS.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/09 09:04
S37	2483	S36 and wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:04
S38	1990	S37 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:04
S39	1174	S38 and bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:05
S40	1067	S39 and @ad<"20040127"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:54

S41	628	S40 and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:56
S42	9592	substrate and bump and pad and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:53
S43	5309	S42 and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:53
S44	3164	S42 and gold	USPAT	OR	ON	2005/09/09 09:54
S45	1362	S44 and wiring	USPAT	OR	ON	2005/09/09 09:54
S46	1358	S45 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:56
S47	230	S46 and S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:50
S48	396	S41 and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 09:56
S49	396	S48 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:29
S50	6966	((257/737,738) or (438/613-617) or (228/180.22)).CCLS.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/09 11:32
S51	2941	S50 and bump and pad and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:31
S52	1649	S51 and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:32

S53	188	S52 and stud	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:34
S54	181	S53 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 11:34
S55	1008382	adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:43
S56	970727	conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:43
S57	280507	paste	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:43
S58	19107	S56 adj S57	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:43
S59	5349	S55 and S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:44
S60	101600	S59 bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:44
S61	101600	S59 or bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:44
S62	1346	S59 and bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:45

S63	1158	S62 and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:45
S64	808	S63 and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:45
S65	701	S64 and @ad<"20040127"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:47
S66	6148	acp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/09 14:48
S67	2965	acp	USPAT	OR	ON	2005/09/09 14:48
S68	2946	S67 and @ad<"20040127"	USPAT	OR	ON	2005/09/09 14:49
S69	174	S68 and substrate and pad	USPAT	OR	ON	2005/09/09 14:49
S70	1	("20020024124").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 10:50
S71	1	("5783465").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 10:57
S72	127	adhesive and ((anistropic adj paste) or ((non-conductive or nonconductive) adj paste))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:47
S73	15	S72 and stud and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 10:59
S74	890	bump and pad and stud and gold and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:50
S75	621	S74 and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:51

S76	115866	S75 and conductive or nonconductive or non-conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:51
S77	585	S75 and (conductive or nonconductive or non-conductive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 11:51
S78	558	S77 and (@ad<"20040127" or @riad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:31
S79	1	("6518667").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 13:34
S80	74578	image adj sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:34
S81	0	anistorpic adj adhesive adj paste	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:34
S82	0	anistropic adj adhesive adj paste	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:35
S83	2	anistropic adj conductive adj paste	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:35
S84	6151	(anistropic adj conductive adj paste) or acp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:37
S85	138	S80 and S84	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:38



S86	5	S85 and bump and stud and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:38
S87	6384	(anisotropic adj conductive adj paste) or acp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:38
S88	138	S80 and S84 and S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:38
S89	174	S80 and S87	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 13:38
S90	6	S89 and bump and stud and gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:16
S91	1771	(438/64,68,113,119).CCLS.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/12 14:16
S92	36	S91 and bump and stud and gold and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 14:17
S93	1	("5783465").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 13:19
S94	0	("20020024124a1").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 13:19
S95	1	("20020024124").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 13:19
S96	0	adhesive and ((anistropic adj paste) and ((non-conductive or nonconductive) adj paste))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:47

S97	3	adhesive and (anistropic adj paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:47
S98	15	adhesive and (anisotropic adj paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:54
S99	1	("6562217").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/13 14:55
S100	5	("3428543"   "4019968"   "5603815"   "5698081").PN. OR ("6562217").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/13 14:57
S101	74622	image adj sensor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 15:53
S102	49	S101 and bump and stud and gold and adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 15:53
S103	21213	adhesive and (nonconductive or non-conductive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:05
S104	20759	S103 and (@ad<"20040127" or @rlad<"20040127")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:06
S105	180	S104 and bump and gold and stud	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:06
S106	2882	(257/680,432,433).CCLS.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/14 10:42
S107	1030	(257/433).CCLS.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	OFF	2005/09/14 10:42

S10 8	24916018	@ad<"20040127"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:42
S10 9	956	S107 and S108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 10:43
S11 0	1	"6582992".PN.	USPAT; USOCR	OR	ON	2005/09/14 10:53